LNJ03004BND3

Surface Mounting Chip LED

3230 Type

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	430	mW
Forward current *1	I_F	120	mA
Pulse forward current *2	I_{FP}	200	mA
Junction temperature	T_j	110	°C
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) ∗1: I_F is different by radiated factor of evaluation board.
This value is mounted on evaluation board at Rthj-a = 35.0 °C/W.
∗2: The condition of pulse current I_{FP} is 55 ms pulse width, 10 % duty.

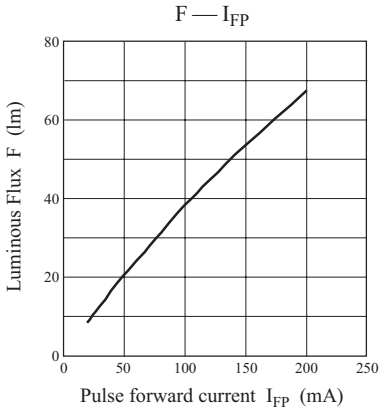
■ Lighting Color

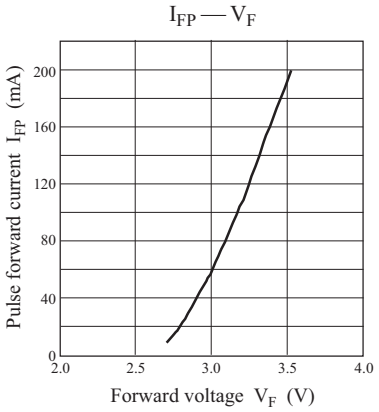
- White (5000 [Kelvin])

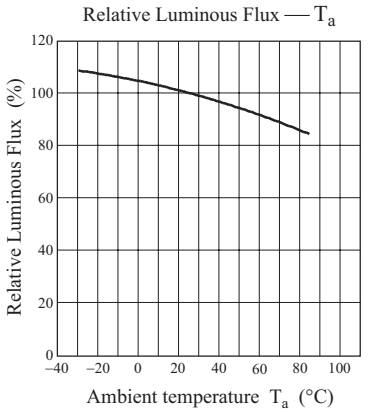
■ Electro-Optical Characteristics T_a = 25°C±3°C

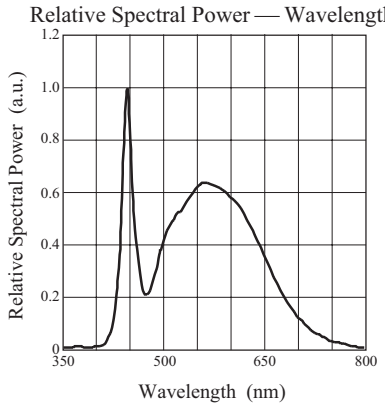
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage *1	V_F	I_{FP} = 60 mA	2.6	3.0	3.4	V
Luminous flux *2	F	I_{FP} = 60 mA	18.0	24.3	36.0	lm
Chromaticity coordinates *3	x	I_{FP} = 60 mA		0.345		—
	y	I_{FP} = 60 mA		0.355		—
Color Rendering Index	Ra	I_{FP} = 60 mA		82		—

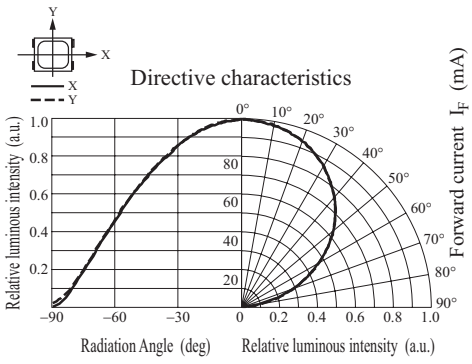
Note) ∗1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance ±3%
∗2: Complete Luminous flux measurement within 0.1 seconds. Tolerance ±10%
∗3: Complete Chromaticity coordinates measurement within 0.1 seconds. Tolerance of chromaticity is ±0.01

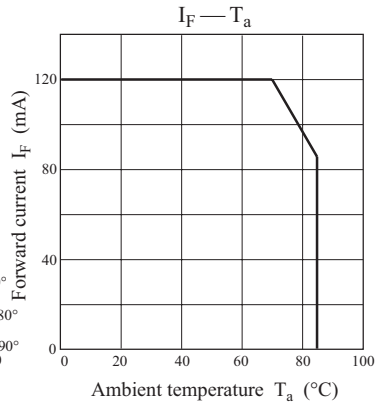




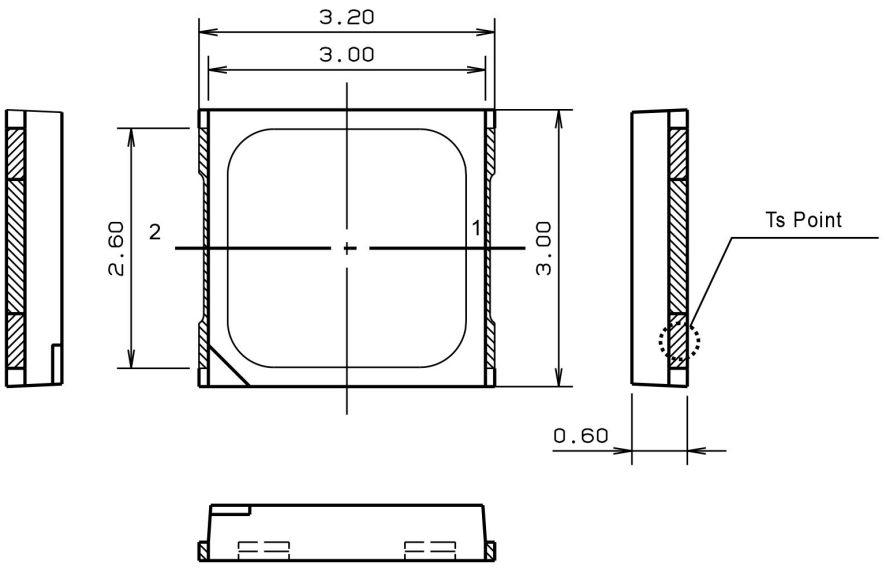


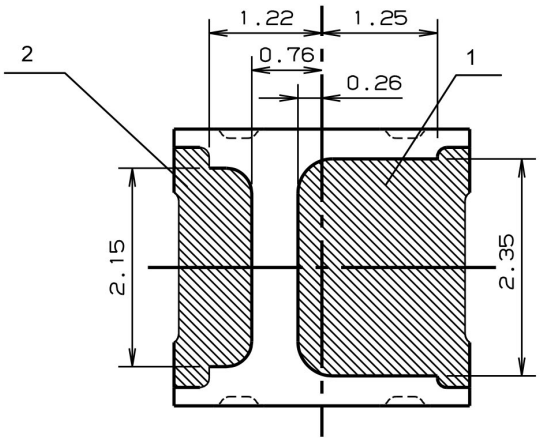


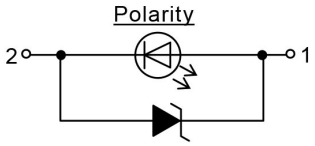




■ Package (Unit: mm)



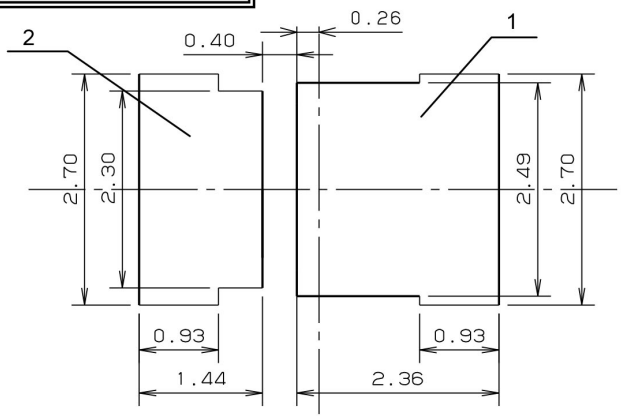




1. Anode
2. Cathode

Item	Contents
Terminal Process	Cu + Ag Plate
Mold Material	Silicone Resin
Package Material	Polymer Base Reflection case

Reference Land Layout



(Note1) Tolerance unless otherwise specified : ±0.2mm

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